

**AMENDMENTS TO THE SPECIFICATION**

At page 1, please replace the “Technical Field” section with the following paragraphs:

Cross-Reference to Related Applications

This application is the U.S. National Phase filing under 35 U.S.C. §371 of PCT/JP2004/018188, filed December 7, 2004, which designated the United States and was published in a language other than English, which claims priority under 35 U.S.C. §119(a)-(d) to Japanese Patent Application Nos. 2003-411762, filed December 10, 2003, and 2004-267161, filed September 14, 2004.. The content of these applications is incorporated herein by reference in their entirety.

Technical Field

The present invention relates to a tape with a built-in IC chip used for a sheet with a built-in IC chip and to a sheet with a built-in IC chip using the tape with a built-in IC chip.